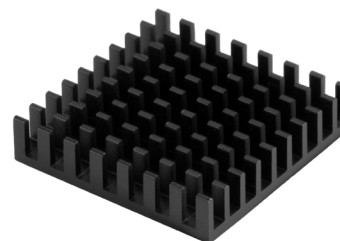




**MODEL:** HSB12-272706 | **DESCRIPTION:** HEAT SINK

**FEATURES**

- BGA design
- top mount
- aluminum alloy
- black anodized finish



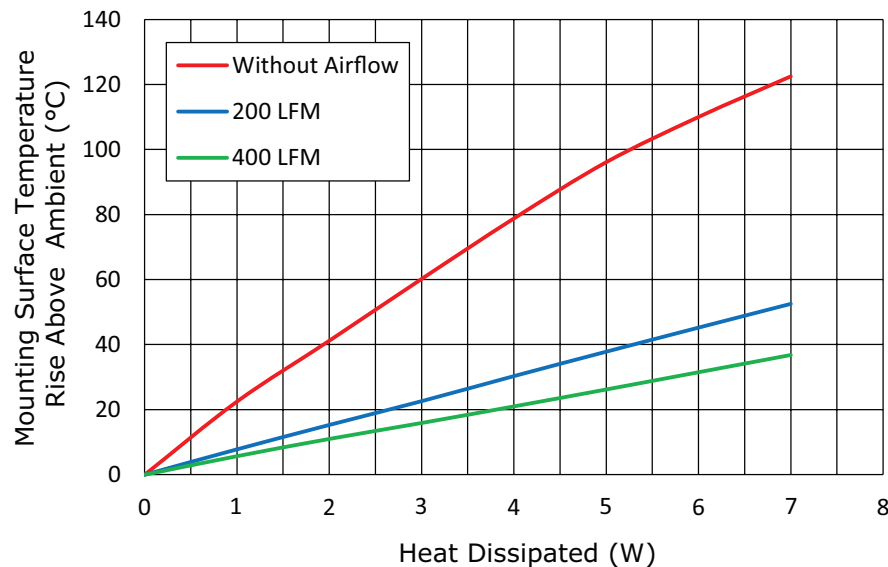
**MODEL**

HSB12-272706	thermal resistance <sup>1</sup>				power dissipation <sup>1</sup>
	@ 75°C ΔT, nat conv [°C/W]	@ 1 W, nat conv [°C/W]	@ 1 W, 200 LFM [°C/W]	@ 1 W, 400 LFM [°C/W]	@ 75°C ΔT, nat conv [W]
	19.59	22.5	7.8	5.7	3.83

Note: 1. See performance curves for full thermal resistance details.

**PERFORMANCE CURVES**

Power (W)	Heatsink Temperature Rise Above Ambient (ΔT = T <sub>hs</sub> - T <sub>a</sub> ) [°C]		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	22.5	7.8	5.7
2	41.2	15.3	11.0
3	60.2	22.6	15.9
4	78.8	30.3	21.0
5	96.1	37.8	26.2
6	110.0	45.2	31.5
7	122.5	52.5	36.8



T<sub>hs</sub>: "hot spot" temperature measured on the heatsink  
 T<sub>a</sub>: ambient temperature

**CUI DEVICES** | **MODEL:** HSB12-272706 | **DESCRIPTION:** HEAT SINK

## MECHANICAL DRAWING

units: mm  
tolerance:  $\pm 0.38$  mm

MATERIAL	AL 6063-T5
FINISH	black anodized
WEIGHT	4.5 g

